

**TRANSMITTAL LETTER  
(General - Patent Pending)**

Docket No.  
**EN9-98-072US2**

In Re Application Of: **Enroth et al.**

Serial No.  
**09/777,976**

Filing Date  
**2/6/01**

Examiner  
**Smith, Sean P.**

Group Art Unit  
**3729**

Title: **WAVE SOLDER APPLICATION FOR BALL GRID ARRAY MODULES**

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TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

TECHNOLOGY CENTER R3700

**Amendment**

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457(IBM)** as described below. A duplicate copy of this sheet is enclosed.
  - ☐ Charge the amount of \_\_\_\_\_
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*Jack P. Friedman*  
Signature

Dated:

*10/1/02*

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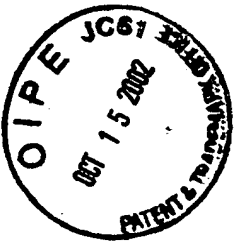
I certify that this document and fee is being deposited on *10/1/02* with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

*Kim Dwileski*  
Signature of Person Mailing Correspondence

**Kim Dwileski**

Typed or Printed Name of Person Mailing Correspondence

CC:



Docket No. EN9-98-072U82

*Handwritten:* 6/Reg for Recrs. 11. 22.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Enroth *et al.*

Group Art Unit: 3729

Filed: 2/6/01

Examiner: Smith, Sean Prentiss

Serial No.: 09/777,976

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Commissioner for Patents  
Washington D.C. 20231

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TECHNOLOGY CENTER R3700

Sir:

This paper is being filed in response to the Office Action mailed July 3, 2002. Applicant's respectfully request that the above-identified application be reconsidered in view of the Amendments and Remarks that follow, that each of the presently pending claims be allowed, and that the application be passed to issue.

**AMENDMENT**

**In The Claims**

Currently pending claims 1-16 are as follows.

1. A method for constructing a printed circuit board assembly, comprising the steps of:
  - (a) providing a printed circuit board comprising:

a top surface comprising a top pad, wherein the top pad is electrically connectable to a top component;